

Features

- Suitable to small packages (SOD-923) Chip Size=0.26mmsq
- High ESD protection level IEC61000-4-2(ESD) +/-30Kv(Contact)
+/-30Kv(Air)

Application

- Cellular phones audio
- MP3 players
- Digital cameras
- Portable applications
- Mobile telephone

Item	Characteristics
Wafer size	5inch
Chip size	260*260um

Maximum Ratings (Ta=25degC)

Symbol	Parameter	Value	Units
Ppk	Peak Power Dissipation @tp=8/20us (*1)		
	RDP5V0	86	W
	RDP6V2	92	W
Pd	Power Dissipation(*1)	150	mW
Tstg	Storage Temperature Range	-55 to+150	Deg C
Tj	Maximum junction temperature (*1)	150	Deg C
Vpp	Electrostatic discharge		
	IEC61000-4-2 air discharge (*1)(*2)	±30	kV
	IEC61000-4-2 contact discharge (*1)	±30	kV

(*1) Rating value for reference on a SOT-23 package configuration (front: Au wire 35um, back: Au eutectic), mounted on PCB of 1.5cm by 2.5cm.

(*2)Reference only

Electrical Characteristics (Ta=25degC)

Ratings at 25degC ambient temperature unless otherwise specified.

Device	V _{RWM} (V) Max	I _R @ V _{RWM} (uA) Max	V _{BR} @1mA (V) Min	V _F @10mA (V) Max	V _c *1 @I _{pp} (V) Max	I _{pp} *1 (A) Max	C *2 @0V (pF) Typ
RDP5V0	3.3	2.5	5.0	0.9	12.3	7.0	45
RDP6V2	5.0	1.0	6.2	0.9	13.2	7.0	40

*1 Package=SOT-23 (front: Au wire 35um, back: Au eutectic) @tp=8/20us

*2 @f=1MHz

Ordering Information

Type	Chip Thickness	Back Metalization	Die Bonding For
RDP5V0J	100um	Au	Eutectic
RDP6V2J	100um	Au	Eutectic

Note
